

# HOW TO REMOVE SOLDER PASTE FROM PRINTING STENCILS, MISPRINTS AND PCBAS





The customer used flammable and aggressive fluid to remove solder paste ALPHA OM-340 88-3-M1 from stencils, misprints, and PCBAs. This type of fluid was unfortunately also highly foaming. The customer's need has been lower VOC, which would be consistent with the set limit, so in this case, we solved ecological problems, but also economical savings.





#### **Our R&D Team Tested Cleaning of:**

## Printing stencils from unsoldered A) ALPHA OM-340 88-3-M1 solder paste

- Misprints of ALPHA OM-340 88-3-M1 B solder paste on PCBs
- PCBAs after soldering process with ALPHA OM-340 88-3-M1 solder paste







ALPHA OM-340 88-3-M1

**Types of Cleaned Components:** 

2 panels of soldered PCBAs

1 panel of PCBs without components





#### **Components Before Cleaning**





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## Water-based cleaning agent **Decotron® CP381**





## Cleaning system Injet® 388 CRD with external filtration





To make mounting of PCBs precise, printing stencils have to be clean! This is the reason why any production should clean printing stencils regularly.



#### **STENCILS BEFORE Cleaning** ->





### **AFTER Cleaning**

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### **MISPRINTS BEFORE Cleaning**









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### **STENCILS + MISPRINTS**

**Cleaning: Decotron® CP381** / 5 min / 40°C / 2,1 bar

**Drip:** 120 s

**Rinsing:** DI Water / 5 min / 30°C

**Drip:** 90 s

**Drying:** hot air / 5 min / 80°C

Total process time: 18,5 min





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### **STENCILS** BEFORE Cleaning --> AFTER Cleaning







#### BEFORE Cleaning -->

#### MISPRINTS











### **PCBs AFTER SOLDERING PROCESS**

**Cleaning: Decotron® CP381** / 10 min / 50°C / 2,1 bar

**Drip:** 120 s

**Rinsing:** DI Water / 10 min / 30°C / 1 µS

**Drip:** 90 s

**Drying:** hot air / 5 min / 80°C

Total process time: 28,5 min



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### **PCBAs BEFORE Cleaning**









### **PCBAs BEFORE Cleaning** ->











We have performed **ROSE** (resistivity of solvent extract) test after cleaning with **Decotron<sup>®</sup> CP381** cleaning agent in **Injet® 388 CRD** cleaning system.

**IPC limit** of ionic contamination (*red line*) corresponds to **1,56 µg NaCl/cm<sup>2</sup>**.

Limit of ionic contamination (green line) is an option to enter your own limit – in this case the limit was not specified by the customer.



# **IONIC CONTAMINATION TEST**



## **Result** of measured ionic contamination (*blue line*) is 0,198 µg NaCl/cm<sup>2</sup>

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# RECOMMENDED **CLEANING AGENT**

### **Decotron® CP381**

in this case study.

- Water-based cleaning fluid
- Determined to clean misprints
- Removes flux residues from PCBs after soldering process
- Intended for use in all types of DCT cleaning system, mainly in high pressure Spray-In-Air cleaning systems





for all three applications with set parameters described



# RECOMMENDED CLEANING SYSTEM

### **InJet® 388 CRD** with external filtration



- STENCIL, MISPRINT, SQUEEGEE cleaning \*\*\*
- **PUMPRINT** cleaning \*\*\*
- **CONFORMAL COATING** removing \*\*\*
- ★★★ **PCB** cleaning





